

**Amendments to the Specification:**

On page 6, please amendment paragraph [0021] as follows:

As best shown by FIGURE 2, heat sink assembly 236 includes heat sinks 262, 263 and heat sink mounting members 264. Heat sinks 263, 262 generally comprise structures thermally coupled to integrated circuit chip 238 of processor assembly 234 and to power supply 237 to dissipate heat generated by processor assembly 234 and by power supply 237, respectively. In the embodiment shown, heat sinks 262, 263 are adjacent the circuit chip and power supply 237. In lieu of distinct heat sinks 262 for processor assembly 234 and for power supply 237, component 224 may utilize a common heat sink for both processor assembly 234 and power supply 237. In one embodiment, a portion of one of heat sinks 262 may extend across and about the other of heat sinks 262. An example of such an arrangement is disclosed in co-pending U.S. Patent Application Serial No. 10/803,399 entitled "Heat Dissipating Arrangement" filed on 03/18/2004 by Stephan K. Barsun, Christian L. Belady, Roy M. Zeighami and Christopher G. Malone, the full disclosure of which is hereby incorporated by reference.